

03-12-2007

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103381163

First Named Inventor

Hong Shan Cheng

Title

Bubble Bottle

Attorney Docket Number

HKPC/425DES/US

Date

March 2, 2007

Mail Stop Assignment Recordation Services Director of the United States Patent and
Trademark Office, P.O. Box 1450, Alexandria, Virginia 22313-1450

Please record the attached document.

1. Name of conveying party(ies):

Hong Shan Cheng

2. Name and address of receiving party(ies):

Name: Lemach Industries Limited
Street Address: Room 16, 20/F, Block C
Wah Lok Industrial Centre
Shan Mei Street, Fotan, Shatin
City, State, ZIP: New Territories, Hong Kong
Country: China

Country of Incorporation: Hong Kong

3. Nature of Conveyance: Assignment
Execution Date: February 5, 2007

4. This document is being filed with a new application,
the execution date of which is: February 5, 2007

5. Name and address of party to whom correspondence document should be mailed:

Guy D. Yale, Esq.
Alix, Yale & Ristas, LLP
750 Main Street, Suite 1400
Hartford, CT 06103-2721

6. Total number of applications involved: 1

7. Total fee enclosed: \$40.00. If this amount is incorrect, please charge or credit the
difference to Deposit Account No. 16-2563.

8. Total number of pages including cover sheet, attachments and documents: 3

To the best of my knowledge and belief, the foregoing information is true and correct.

SIGNATURE OF APPLICANT, ATTORNEY OR AGENT

Firm or

Individual name

Guy D. Yale

Reg. No.

29,125

Signature

March 2, 2007

Attorney's Docket No.

HKPC/425DES/US

40.00 DP

EV196539485US

PATENT

REEL: 019008 FRAME: 0077

112956 U.S. PTO
29/273312
030207

03/09/2007
01 FC:8021

Attorney Docket: HKPC/425DES/US

ASSIGNMENT

WHEREAS, I, Hong Shan Cheng, residing at Room 16, 20/F, Block C, Wah Lok Industrial Centre, Shan Mei Street, Fotan, Shatin, New Territories, Hong Kong, China, have invented new and useful improvements in

Bubble Bottle

for which I am making application for Letters Patent of the United States, which application was executed by me on the _____ day of _____ 2007; and

WHEREAS, Lemach Industries Limited, a Hong Kong corporation, having a place of business at Room 16, 20/F, Block C, Wah Lok Industrial Centre, Shan Mei Street, Fotan, Shatin, New Territories, Hong Kong, China, is desirous of acquiring the entire right, title and interest in and to said improvements and any Letters Patent which may be granted thereon;

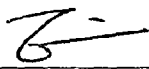
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in consideration of the sum of One Dollar (\$1.00) to me in hand paid and other good and valuable consideration, receipt of which is hereby acknowledged, I, the said Hong Shan Cheng, sell, assign and transfer to Lemach Industries Limited, its successors and assigns (hereinafter called "Assignee"), the entire right, title and interest in and to said improvements and in and to any Letters Patent which may be obtained thereon in the United States, together with said application and all divisional, continuing, substitute, renewal, reissue, and other applications for Letters Patent which have been or may be filed on said improvements in the United States, the same to be held and enjoyed by the Assignee for its and their sole use and behoof.

I hereby authorize and request the Commissioner of Patents and Trademarks to issue all Letters Patent of the United States on said improvements to the Assignee.

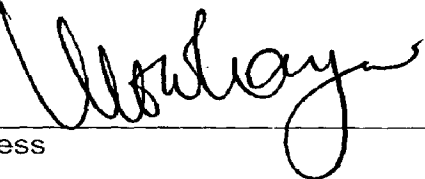
I further covenant and agree that when requested by the Assignee, and without further consideration, but at the cost and expense of the Assignee, I will execute and deliver all applications for patent on said improvements, execute all lawful oaths and other papers, supply to the Assignee all facts and evidence known to me relating to said improvements and the history and development thereof, testify in all interferences, suits, and other legal proceedings, and generally do everything rightful which the Assignee shall consider desirable for aiding in securing, maintaining, and enforcing proper patent protection for said improvements and for vesting the title to said improvements in the Assignee.

I further covenant that I have the lawful right to assign the interest in said improvements in the manner and form as herein expressed, that the interests herein conveyed are free from prior assignment, grant, mortgage, license, or other encumbrance whatsoever and that the execution of this Assignment is my own free act and deed.

Date: 5 Feb 2007


Hong Shan Cheng


Witness


Witness